

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Kazuto HIROKAWA et al. : **Attn: APPLICATION BRANCH**
Serial No. NEW : Attorney Docket No. 2003-0961A
Filed July 14, 2003 :
SUBSTRATE POLISHING APPARATUS

**COVER LETTER ACCOMPANYING APPLICATION FILED WITHOUT EXECUTED
DECLARATION UNDER 37 CFR 1.53(b) AND IN A LANGUAGE
OTHER THAN ENGLISH UNDER 37 CFR 1.52(d)**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Enclosed is a new patent application entitled "SUBSTRATE POLISHING APPARATUS". This application is submitted in the Japanese language under the provisions of 37 CFR 1.52(d).

Furthermore, the present application is submitted under the provisions of 37 CFR 1.53(b), and the application as filed does not include an executed declaration. However, accompanying the application is an unexecuted declaration listing the inventor information.

The application as filed further does not include an executed power of attorney, and accordingly, it is requested that communication initially be directed to the following firm, until an executed power of attorney and declaration are filed:

WENDEROTH, LIND & PONACK, L.L.P.
2033 K Street, N.W., Suite 800
Washington, D.C. 20006-1021

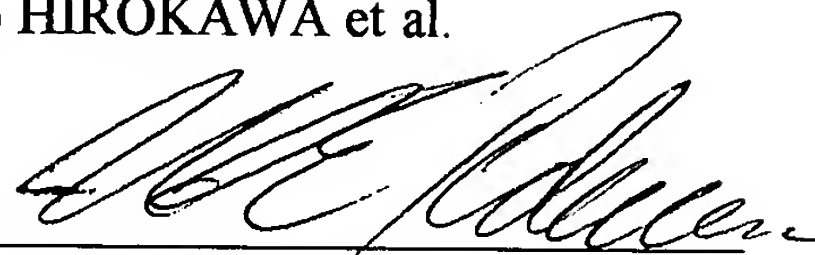
Telephone: (202) 721-8200
Facsimile: (202) 721-8250

The required filing fee of \$750.00 is enclosed.

Respectfully submitted,

Kazuto HIROKAWA et al.

By



Nils E. Pedersen

Registration No. 33,145

Attorney for Applicants

NEP/krl

Washington, D.C. 20006-1021

Telephone (202) 721-8200

Facsimile (202) 721-8250

July 14, 2003

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

(X) Original () Supplemental () Substitute () PCT () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: SUBSTRATE POLISHING APPARATUS

of which is described and claimed in:

(X) the attached specification, or

() the specification in application Serial No. _____, filed _____, and with amendments through __, or

() the specification in International Application No. _____, filed _____, and as amended on _____ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:


COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2003-138479	May 16, 2003	YES
Japan	2003-138496	May 16, 2003	YES
Japan	2003-138782	May 16, 2003	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; and Jeffrey R. Filipek, Reg. No. 41,471, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from WATANABE & HOTTA as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Direct Correspondence to Customer No: <div style="text-align: center;">  000513 PATENT TRADEMARK OFFICE </div>		Direct Telephone Calls to: WENDEROTH, LIND & PONACK, L.L.P. 2033 "K" Street, N.W., Suite 800 Washington, D.C. 20006-1021 Phone: (202) 721-8200 Fax: (202) 721-8250	
---	--	---	--

Full Name of First Inventor	FAMILY NAME HIROKAWA	FIRST GIVEN NAME Kazuto	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan		

Full Name of Second Inventor	FAMILY NAME NAKAI	FIRST GIVEN NAME Shunsuke	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan		

Full Name of Third Inventor	FAMILY NAME OHTA	FIRST GIVEN NAME Shinro	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan		

Full Name of Fourth Inventor	FAMILY NAME WADA	FIRST GIVEN NAME Yutaka	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan		

Full Name of Fifth Inventor	FAMILY NAME KOBAYASHI	FIRST GIVEN NAME Yoichi	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan

Post Office Address	ADDRESS	CITY	STATE OR COUNTRY	ZIP CODE
	c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan			
Full Name of Sixth Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME	
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP	
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY	ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor _____ Date _____
Kazuto HIROKAWA

2nd Inventor _____ Date _____
Shunsuke NAKAI

3rd Inventor _____ Date _____
Shinro OHTA

4th Inventor _____ Date _____
Yutaka WADA

5th Inventor _____ Date _____
Yoichi KOBAYASHI

6th Inventor _____ Date _____

The above application may be more particularly identified as follows:

U.S. Application Serial No. NEW Filing Date July 14, 2003

Applicant Reference Number GEB1956-US Atty Docket No. 2003-0961A

Title of Invention SUBSTRATE POLISHING APPARATUS